

Title (en)

Enhanced printer device alignment method and apparatus

Title (de)

Verbessertes Druckgerätausrichtungsverfahren und -apparat

Title (fr)

Méthode d'alignement améliorée pour dispositif d'impression et appareil correspondant

Publication

EP 1245399 A2 20021002 (EN)

Application

EP 01121159 A 20010904

Priority

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- EP 01108128 A 20010330

Abstract (en)

A method of determining a registration offset in a hard copy apparatus, the apparatus comprising a pen arranged to mark a print medium and a sensor arranged to detect marks on the medium along a sensor path, the method comprising the steps of: marking a alignment pattern on the medium, the pattern being at least partially located along the sensor path; detecting the position along the sensor path of a portion of the pattern; and, determining a distance by which the pattern is offset from the sensor path in a direction substantially perpendicular to the sensor path, the pattern being configured such that the detected position is indicative of the offset distance.

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CPC (source: EP US)

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Citation (applicant)

- US 5796414 A 19980818 - SIEVERT OTTO K [US], et al
- EP 0895869 A2 19990210 - SEIKO EPSON CORP [JP]

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